

LI-M114-FF SPECIFICATION

**Rev 1.1
Leopard Imaging Inc.**

Contents

Version History	3
Key Information	4
Pin Assignment	5
Electrical Characteristics	6
1. Absolute Maximum Ratings	6
2. Operating Conditions.....	6
3. DC Characteristics.....	6
4. Operating Current Consumption	7
5. Standby Current Consumption	8
6. AC Electrical Characteristics.....	8
7. Two-Wire Serial Bus Timing Parameters	9
8. Two-Wire Serial Interface Timing Data	9
9. Power-Up and Power-Down Sequence	10
10. Typical Quantum Efficiency	10
Mechanical Drawing	11



LI-M114-FF SPECIFICATION

Version History

Version	Description	Release Date
1.0	First Release	9. Feb. 2015
1.1	Change the Lens (V1.4 module)	16. Mar. 2015



LI-M114-FF SPECIFICATION

Key Information

Module Part#		LI-M114-FF
Module Size		90 mm (L) x 5.6 mm (W) x 3.9 mm(H)
Sensor Type		MT9M114
Array Size		1296 x 976
Supply Voltage	Digital	1.7 ~ 1.95V
	Analog	2.5 ~ 3.1V
	I/O	1.7 ~ 1.95 V or 2.5 ~ 3.1 V
	PLL	2.5 ~ 3.1 V
	PHY	1.7 ~ 1.95V
Optical format		1/6"
Focus(F.NO)		2.8
FOV (D)		60°
Focal Length		2.54 mm
Focusing Range		30cm to infinity
TV Distortion		< 1 %
Pixel size		1.9 um x 1.9 um
Color filter array		RGB Bayer
Output format		YUV
Operating temperature		-30 °C to +70 °C
Max. Frame Rate		30 fps full resolution, 36.7 fps 720p, 75 fps VGA , 120 fps QVGA2
Dynamic Range		70.8 dB
Max S/N ratio		37 dB
Responsivity		2.24 V/lux-sec(550 nm)
Shutter type		Electronic rolling shutter (ERS)
Power consumption		135 mW (for typical voltages and 720p output)
Input clock range		6 ~ 54MHz
Output pixel clock maximum		96 MHz



LI-M114-FF SPECIFICATION

Pin Assignment

No.	Name	Pin type	Description
1	DGND	Ground	Digital ground
2	DOVDD1.8V/2.8V	Power	Power for I/O circuit
3	DGND	Ground	Digital ground
4	DGND	Ground	Digital ground
5	DOVDD1.8V/2.8V	Power	Power for I/O circuit
6	SDA	I/O	Two-wire serial interface data
7	DVDD1.8V	Power	Digital Power
8	SCL	Input	Two-wire serial interface clock
9	PWDN(NC)	NC	
10	DGND	Ground	Digital ground
11	RESET	Input/PU	Master reset signal, active LOW. This signal has an internal pull up
12	CLK-N	Output	Differential MIPI clock (sub-LVDS, negative)
13	DGND	Ground	Digital ground
14	CLK-P	Output	Differential MIPI clock (sub-LVDS, positive)
15	MCLK	Input	Master clock
16	DATA-N	Output	Differential MIPI data (sub-LVDS, negative)
17	DGND	Ground	Digital ground
18	DATA-P	Output	Differential MIPI data (sub-LVDS, positive)
19	AGND	Ground	Analog ground
20	DGND	Ground	Digital ground
21	AVDD2.8	Power	Analog power
22	DGND	Ground	Digital ground
23	AGND	Ground	Analog ground
24	DGND	Ground	Digital ground



LI-M114-FF SPECIFICATION

Electrical Characteristics

1. Absolute Maximum Ratings

Symbol	Parameter	Rating		Unit
		Min	Max	
VDD_MAX	Core digital voltage	-0.3	2.4	V
VDD_IO_MAX	I/O digital voltage	-0.3	4.0	V
VAA_MAX	Analog voltage	-0.3	4.0	V
VDD_PLL_MAX	PLL supply voltage	-0.3	4.0	V
VDD_PHY_MAX	PHY supply voltage	-0.3	2.4	V
VIN	DC input voltage	-0.3	VDD_IO + 0.3	V
IIN	Transient input current (0.5 sec. duration)	-	150	mA
T _{OP}	Operating temperature (measure at junction)	-30	75	°C
T _{STG} ¹	Storage temperature	-40	85	°C

Notes: 1. This is a stress rating only, and functional operation of the device at these or any other conditions above those indicated in the product specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2. Operating Conditions

Symbol	Parameter	Min	Typ	Max	Units
VDD	Core digital voltage	1.7	1.8	1.95	V
VDD_IO	I/O digital voltage	2.5	2.8	3.1	V
		1.7	1.8	1.95	V
VAA	Analog voltage	2.5	2.8	3.1	V
VDD_PLL	PLL supply voltage	2.5	2.8	3.1	V
VDD_PHY	PHY supply voltage	1.7	1.8	1.95	V
T _j	Operating temperature (at junction)	-30	55	70	°C

3. DC Characteristics

Symbol	Parameter	Condition	Min	Max	Unit	Notes
V _{IH}	Input HIGH voltage		VDD_IO * 0.7	-	V	1
V _{IL}	Input LOW voltage		-	VDD_IO * 0.3	V	1
I _{IN}	Input leakage current	V _{IN} = 0V or V _{IN} = VDD_IO		10	μA	2
V _{OH}	Output HIGH voltage	I _{OH} = 2 mA	VDD_IO * 0.75		V	
V _{OL}	Output LOW voltage	I _{OH} = 2 mA	-	VDD_IO * 0.25	V	

Notes: 1. V_{IL} and V_{IH} have min/max limitations specified by absolute ratings.
2. Excludes CONFIG and RESET_BAR as they have an internal pull-up resistor.



LI-M114-FF SPECIFICATION

4. Operating Current Consumption

Default Setup Conditions: $f_{EXTCLK} = 24 \text{ MHz}$, $f_{PIXCLK} = 96 \text{ MHz}$, $V_{AA} = V_{DD_IO} = V_{DD_PLL} = 2.8\text{V}$,

$V_{DD} = V_{DD_PHY} = 1.8\text{V}$, $T_j = 70^\circ\text{C}$ unless otherwise stated, PN9 enabled, specified under MIPI and Parallel output conditions

Symbol	Conditions	Min	Typ	Max	Unit
VDD		1.7	1.8	1.95	V
VAA		2.5	2.8	3.1	V
VDD_PHY		1.7	1.8	1.95	V
VDD_PLL		2.5	2.8	3.1	V
VDD_IO	VDD_IO = 2.8V	2.5	2.8	3.1	V
	VDD_IO = 1.8V	1.7	1.8	1.95	V
IDD	Full resolution 30 fps, parallel		39	50	mA
	720p, 30 fps, parallel		33	45	mA
	VGA binned, 60 fps, parallel		25	40	mA
	Full resolution, 30fps, MIPI		39	50	mA
	720p, 30 fps, MIPI		33	45	mA
	VGA binned, 60 fps, MIPI		25	40	mA
IAA	Full resolution, 30 fps, parallel		19	35	mA
	720p, 30 fps, parallel		19	35	mA
	VGA binned, 60 fps, parallel		19	35	mA
	Full resolution, 30 fps, MIPI		19	35	mA
	720p, 30 fps, MIPI		19	35	mA
	VGA binned, 60 fps, MIPI		19	35	mA
IDD_PLL	Full resolution, 30 fps, parallel		8	20	mA
	720p, 30 fps, parallel		8	20	mA
	VGA, 60 fps, parallel		8	20	mA
	Full resolution, 30fps, MIPI		25	40	mA
	720p, 30 fps, MIPI		25	40	mA
	VGA binned, 60 fps, MIPI		25	40	mA
IDD_PHY	Full resolution, 30 fps, parallel		0.02	0.5	mA
	720p, 30fps, parallel		0.02	0.5	mA
	VGA binned, 60 fps, parallel		0.02	0.5	mA
	Full resolution, 30 fps, MIPI		0.18	1	mA
	720p, 30 fps, MIPI		0.18	1	mA
	VGA binned, 60 fps, MIPI		0.18	1	mA
Total power consumption ¹	Full resolution, 30 fps, parallel		146		mW
	720p, 30fps, parallel		135		mW
	VGA binned, 60 fps, parallel		121		mW
	Full resolution, 30 fps, MIPI		194		mW
	720p, 30 fps, MIPI		183		mW
	VGA binned, 60 fps, MIPI		169		mW

Notes: 1. Total power excludes VDD_IO current.



LI-M114-FF SPECIFICATION

5. Standby Current Consumption (Parallel and MIPI)

Default Setup Conditions: $f_{EXTCLK}=24$ MHz, $f_{PIXCLK}=96$ MHz, $V_{AA} = V_{DD_IO} = V_{DD_PLL} = 2.8$ V, $V_{DD} = V_{DD_PHY} = 1.8$ V, $T_j = 70^\circ\text{C}$ unless otherwise stated

		Typical	Max	Unit
Soft Standby (CLK ON)	Total standby current in parallel and MIPI mode	1.4	3	mA
	Total power consumption in parallel and MIPI mode	2.5		mW
Soft Standby (CLK OFF)	Total standby current in parallel and MIPI mode	80	500	μA
	Total power consumption in parallel and MIPI mode	150		μW

Note: All power measurements exclude IO current.

6. AC Electrical Characteristics

EXTCLK = 6–54 MHz; $V_{DD} = V_{DD_PHY} = 1.8$ V; $V_{DD_IO} = V_{AA} = V_{DD_PLL} = 2.8$ V; $T_j = 25^\circ\text{C}$ unless otherwise stated

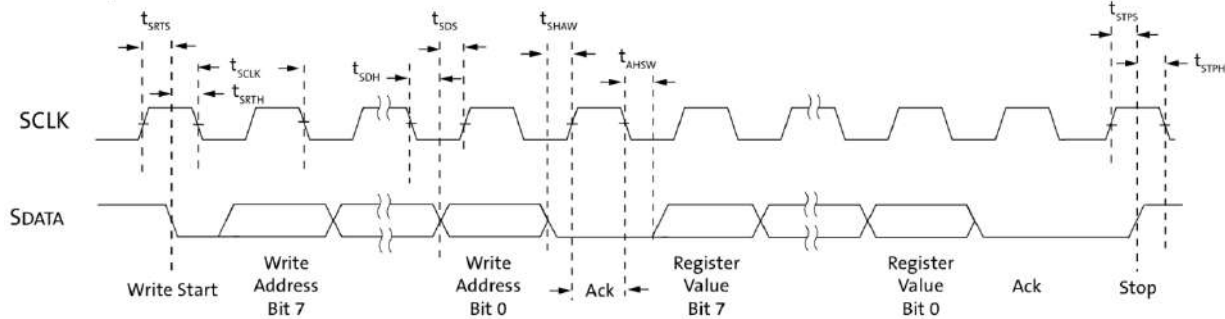
Symbol	Parameter	Conditions	Min	Typ	Max	Unit	Notes
f_{EXTCLK}	External clock frequency		6		54	MHz	1
D_{EXTCLK}	External input clock duty cycle		40	50	60	%	
t_{JITTER}	External input clock jitter		–	500	–	ps	2
t_{PD}	PIXCLK to data valid		–	2	5	ns	
t_{PFH}	PIXCLK to FV HIGH		–	2	5	ns	
t_{PLH}	PIXCLK to LV HIGH		–	2	5	ns	
t_{PFL}	PIXCLK to FV LOW		–	2	5	ns	
t_{PLL}	PIXCLK to LV LOW		–	2	5	ns	
t_{CP}	EXTCLK TO PIXCLK propagation delay	$t_{PIXCLK} = \text{PIXCLK period}$		$0.1 \times t_{PIXCLK}$		ns	
PIXCLK slew rate							
	Slew = 4	$V_{DD_IO} = 2.8$ V, PLL bypass, 6 MHz EXTCLK, $C_{LOAD} = 35$ pF	–	0.647	–	V/ns	
		$V_{DD_IO} = 1.8$ V, PLL bypass, 6 MHz EXTCLK, $C_{LOAD} = 35$ pF	–	0.27	–	V/ns	
Output slew rate							
	Slew = 4	$V_{DD_IO} = 2.8$ V, PLL bypass, 6 MHz EXTCLK, $C_{LOAD} = 35$ pF	–	0.229	–	V/ns	
		$V_{DD_IO} = 1.8$ V, PLL bypass, 6 MHz EXTCLK, $C_{LOAD} = 35$ pF	–	0.112	–	V/ns	

- Notes:
- V_{IH}/V_{IL} restrictions apply.
 - Based on lab measurements. Could vary with noisier system-level electronics.

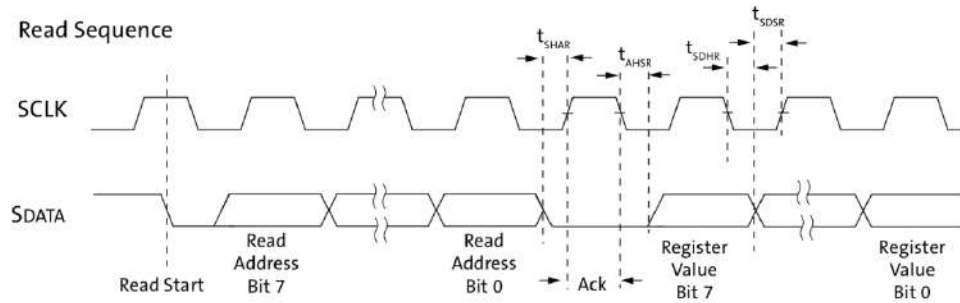


7. Two-Wire Serial Bus Timing Parameters

Write Sequence



Read Sequence



8. Two-Wire Serial Interface Timing Data

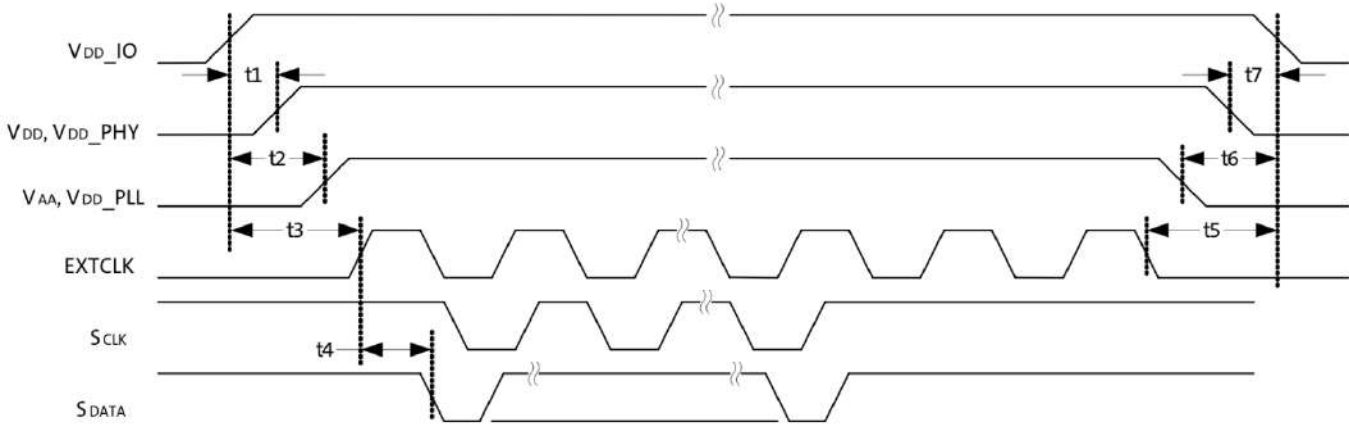
$f_{EXTCLK} = 50 \text{ MHz}$; $V_{DD} = 1.8\text{V}$; $V_{DD_IO} = 1.8\text{V}$; $V_{AA} = 2.8\text{V}$; $T_j = 70^\circ\text{C}$; $C_{LOAD} = 68.5\text{pF}$

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_{SCLK}	Serial interface input clock frequency		100	–	400	kHz
t_{SCLK}	Serial interface input clock period		10	–	2.5	μs
	SCLK duty cycle		45	50	55	%
t_r	SCLK/SDATA rise time		–	–	300	ns
t_{SRTS}	Start setup time	Master write to slave	600	–	–	
t_{SRTH}	Start hold time	Master write to slave	300	–	–	ns
t_{SDH}	SDATA hold	Master write to slave	300	–	650	ns
t_{SDS}	SDATA setup	Master write to slave	300	–	–	ns
t_{SHAW}	SDATA hold to ack	Master write to slave	150	–	–	ns
t_{AHSW}	Ack hold to SDATA	Master write to slave	150	–	–	ns
t_{STPS}	Stop setup time	Master write to slave	300	–	–	ns
t_{STPH}	Stop hold time	Master write to slave	600	–	–	ns
t_{SHAR}	SDATA hold to ack	Master read from slave	300	–	–	ns
t_{AHSR}	Ack hold to SDATA	Master read from slave	300	–	–	ns
t_{SDHR}	SDATA hold	Master read from slave	300	–	650	ns
t_{SDSR}	SDATA setup	Master read from slave	350	–	–	ns



LI-M114-FF SPECIFICATION

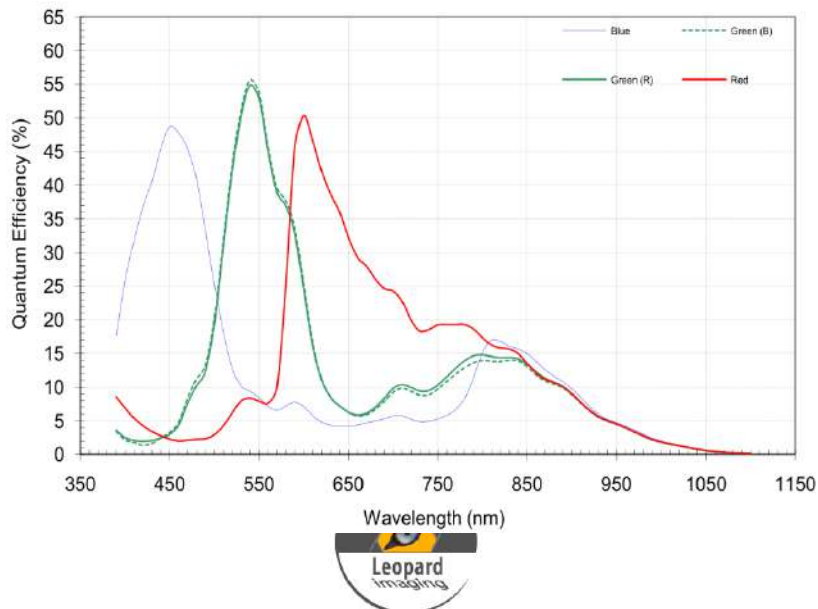
9. Power-Up and Power-Down Sequence



Symbol	Parameter	Min	Typ	Max	Unit
t1	Delay from VDD_IO to VDD and VDD_PHY	0	–	50	ms
t2	Delay from VDD_IO to VAA and VDD_PLL	0	–	50	ms
t3	EXTCLK activation	t2	–	–	ms
t4	First serial command ^{1, 2}	–	44.5	–	ms
t5	EXTCLK cutoff	t6	–	–	ms
t6	Delay from VAA and VDD_PLL to VDD_IO	0	–	50	ms
t7	Delay from VDD and VDD_PHY to VDD_IO	0	–	50	ms

- Notes: 1. Under the condition of EXTCLK=24MHz and default settings with CONFIG=1.
 2. The host should poll the Command register to determine when the device is initialized.

10. Typical Quantum Efficiency



LI-M114-FF SPECIFICATION

